

# SN5408, SN54LS08, SN54S08 SN7408, SN74LS08, SN74S08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

SDLS033 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

## description

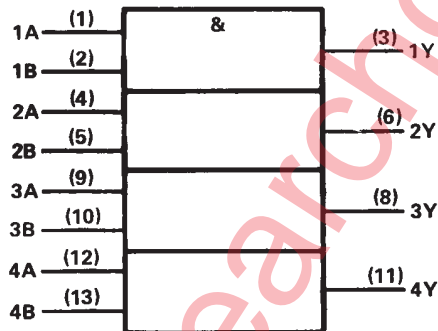
These devices contain four independent 2-input AND gates.

The SN5408, SN54LS08, and SN54S08 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN7408, SN74LS08 and SN74S08 are characterized for operation from  $0^{\circ}$  to  $70^{\circ}\text{C}$ .

FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

## logic symbol†

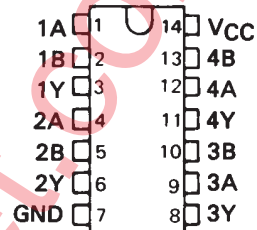


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

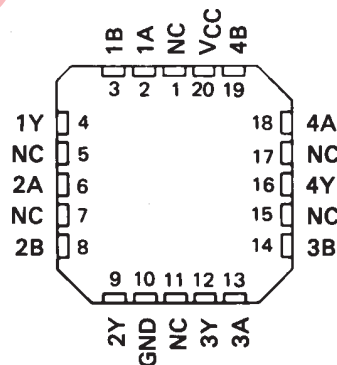
SN5408, SN54LS08, SN54S08 . . . J OR W PACKAGE  
SN7408 . . . J OR N PACKAGE  
SN74LS08, SN74S08 . . . D, J OR N PACKAGE

(TOP VIEW)



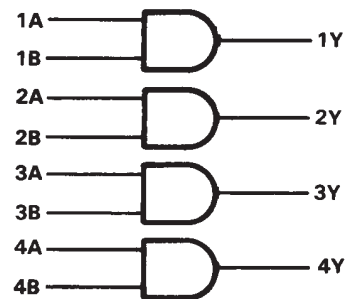
SN54LS08, SN54S08 . . . FK PACKAGE

(TOP VIEW)



NC—No internal connection

## logic diagram (positive logic)

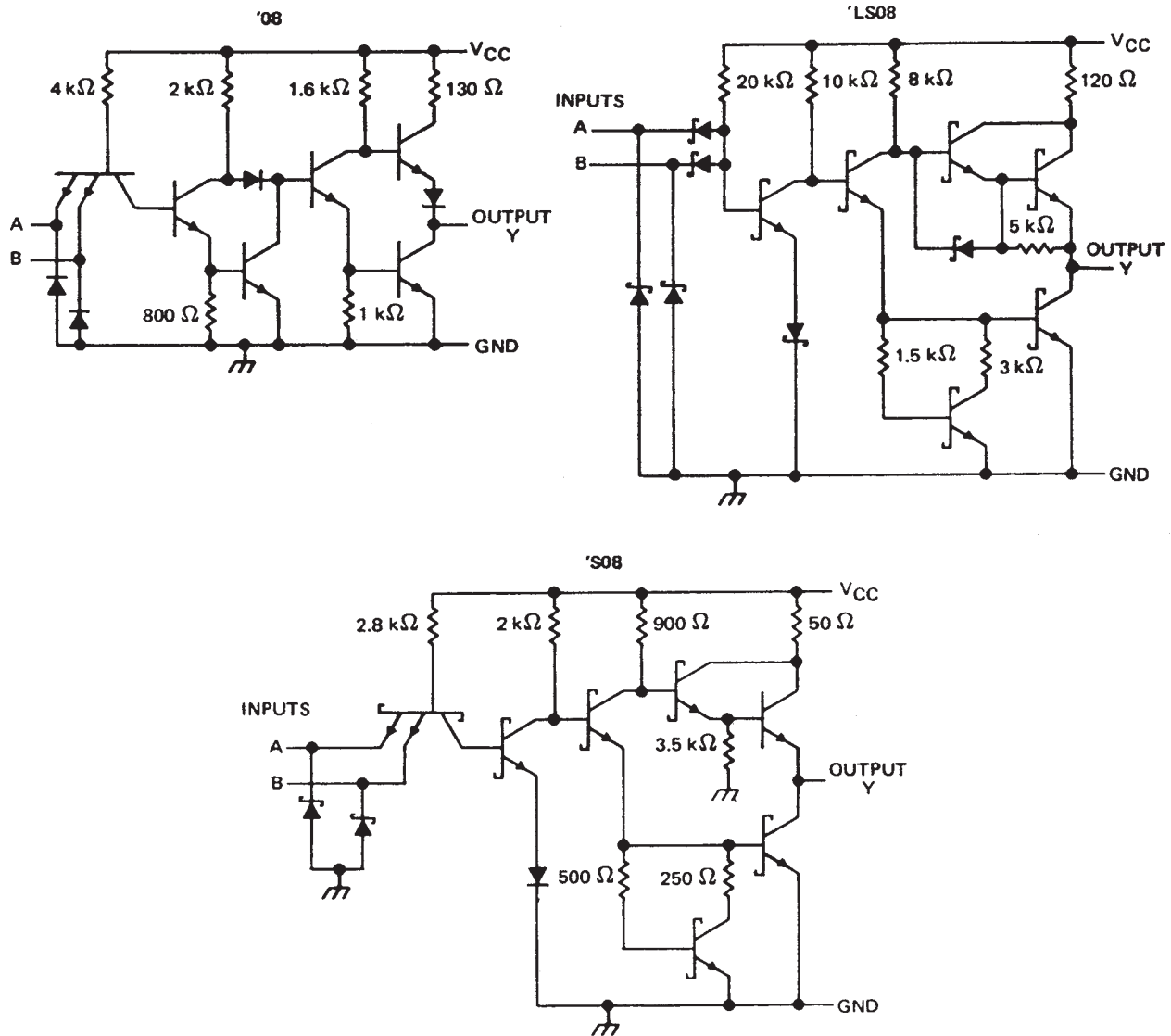


$$Y = A \cdot B \text{ or } Y = \overline{\overline{A} + \overline{B}}$$

# SN5408, SN54LS08, SN54S08 SN7408, SN74LS08, SN74S08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

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## schematics (each gate)



Resistor values are nominal.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage: '08, 'S08	5.5 V
'LS08	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN5408, SN54LS08, SN54S08  
SN7408, SN74LS08, SN74S08  
**QUADRUPLE 2-INPUT POSITIVE-AND GATES**  
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**recommended operating conditions**

	SN5408			SN7408			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.8			0.8	V
I <sub>OH</sub> High-level output current			-0.8			-0.8	mA
I <sub>OL</sub> Low-level output current			16			16	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS †	SN5408			SN7408			UNIT
		MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 mA			-1.5			-1.5	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -0.8 mA	2.4	3.4		2.4	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V			40			40	μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-1.6			-1.6	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-20		-55	-18		-55	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		11	21		11	21	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		20	33		20	33	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	Y	R <sub>L</sub> = 400 Ω, C <sub>L</sub> = 15 pF		17.5	27	ns
t <sub>PHL</sub>					12	19	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

**SN5408, SN54LS08, SN54S08  
SN7408, SN74LS08, SN74S08  
QUADRUPLE 2-INPUT POSITIVE-AND GATES**

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**recommended operating conditions**

	SN54LS08			SN74LS08			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.7			0.8	V
I <sub>OH</sub> High-level output current			-0.4			-0.4	mA
I <sub>OL</sub> Low-level output current			4			8	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS †	SN54LS08			SN74LS08			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.5			-1.5	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -0.4 mA	2.5	3.4		2.7	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OL</sub> = 8 mA					0.35	0.5	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V			0.1			0.1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			20			20	μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-0.4			-0.4	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-20		-100	-20		-100	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		2.4	4.8		2.4	4.8	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		4.4	8.8		4.4	8.8	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	Y	R <sub>L</sub> = 2 kΩ, C <sub>L</sub> = 15 pF		8	15	ns
t <sub>PHL</sub>					10	20	

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



SN5408, SN54LS08, SN54S08  
SN7408, SN74LS08, SN74S08  
**QUADRUPLE 2-INPUT POSITIVE-AND GATES**  
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**recommended operating conditions**

	SN54S08			SN74S08			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.8			0.8	V
I <sub>OH</sub> High-level output current			-1			-1	mA
I <sub>OL</sub> Low-level output current			20			20	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS †	SN54S08			SN74S08			UNIT
		MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.2			-1.2	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -1 mA	2.5	3.4		2.7	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA			0.5			0.5	V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			50			50	μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V			-2			-2	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-40		-100	-40		-100	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		18	32		18	32	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		32	57		32	57	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	Y	R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 15 pF	4.5		7	ns
t <sub>PHL</sub>				5		7.5	ns
t <sub>PLH</sub>			R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 50 pF	6			ns
t <sub>PHL</sub>				7.5			ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/08003BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/08003BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/08003BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/31004B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/31004BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7408N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7408N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7408N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7408N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74LS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S08N	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						(RoHS)		
SN74S08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

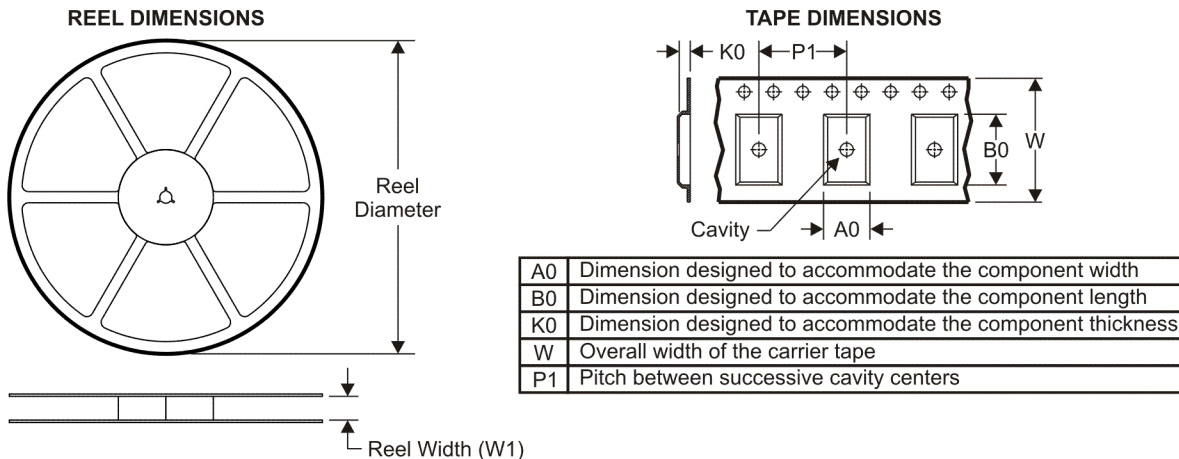
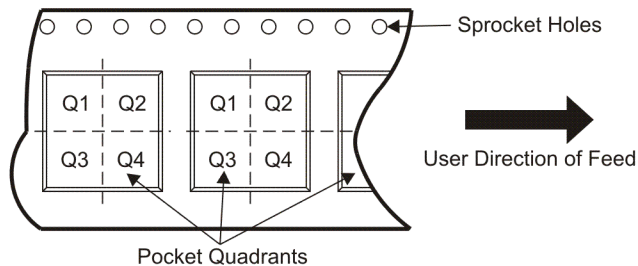
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI



to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS08DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS08NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS08DBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LS08DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS08NSR	SO	NS	14	2000	346.0	346.0	33.0

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



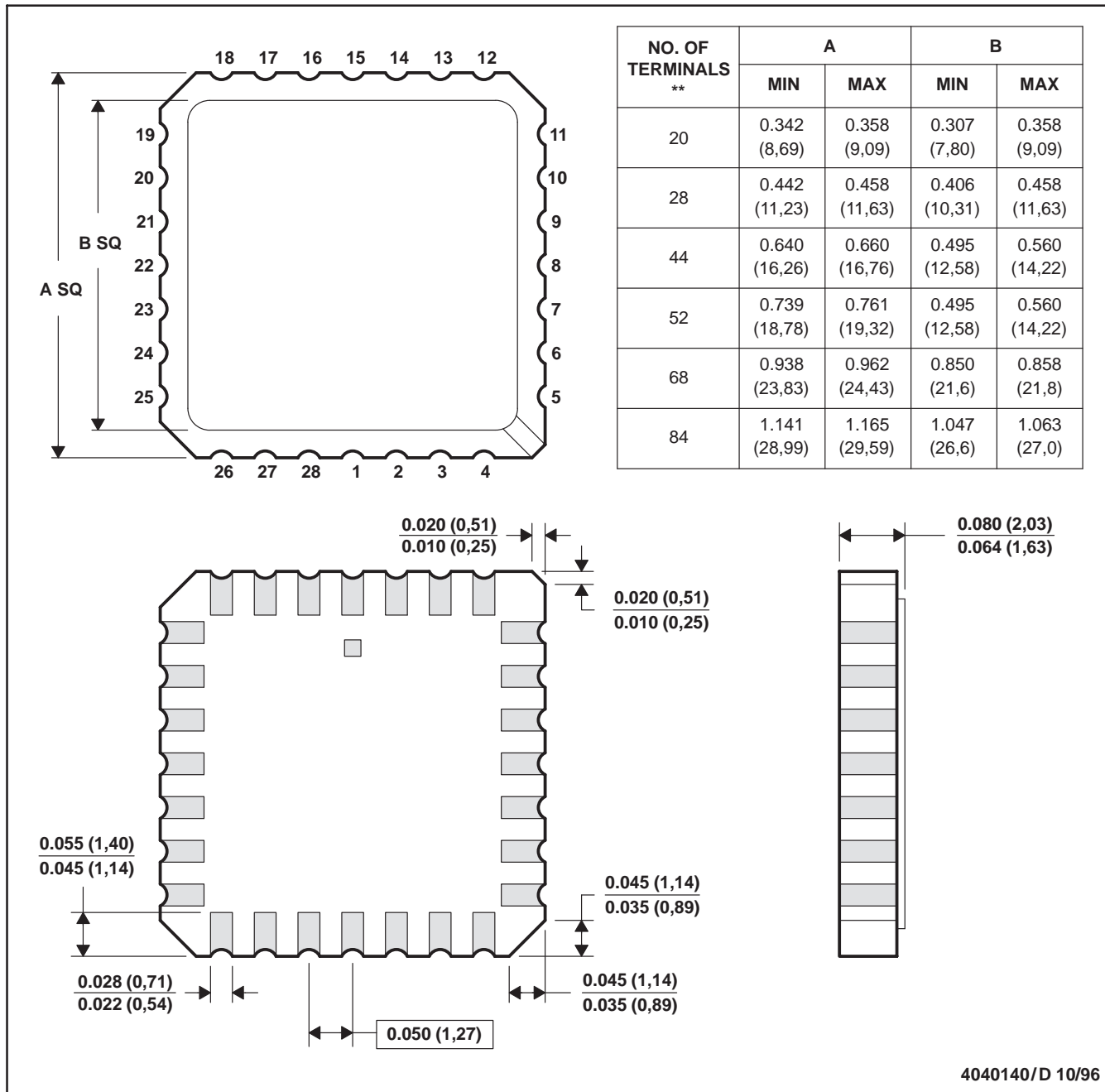
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

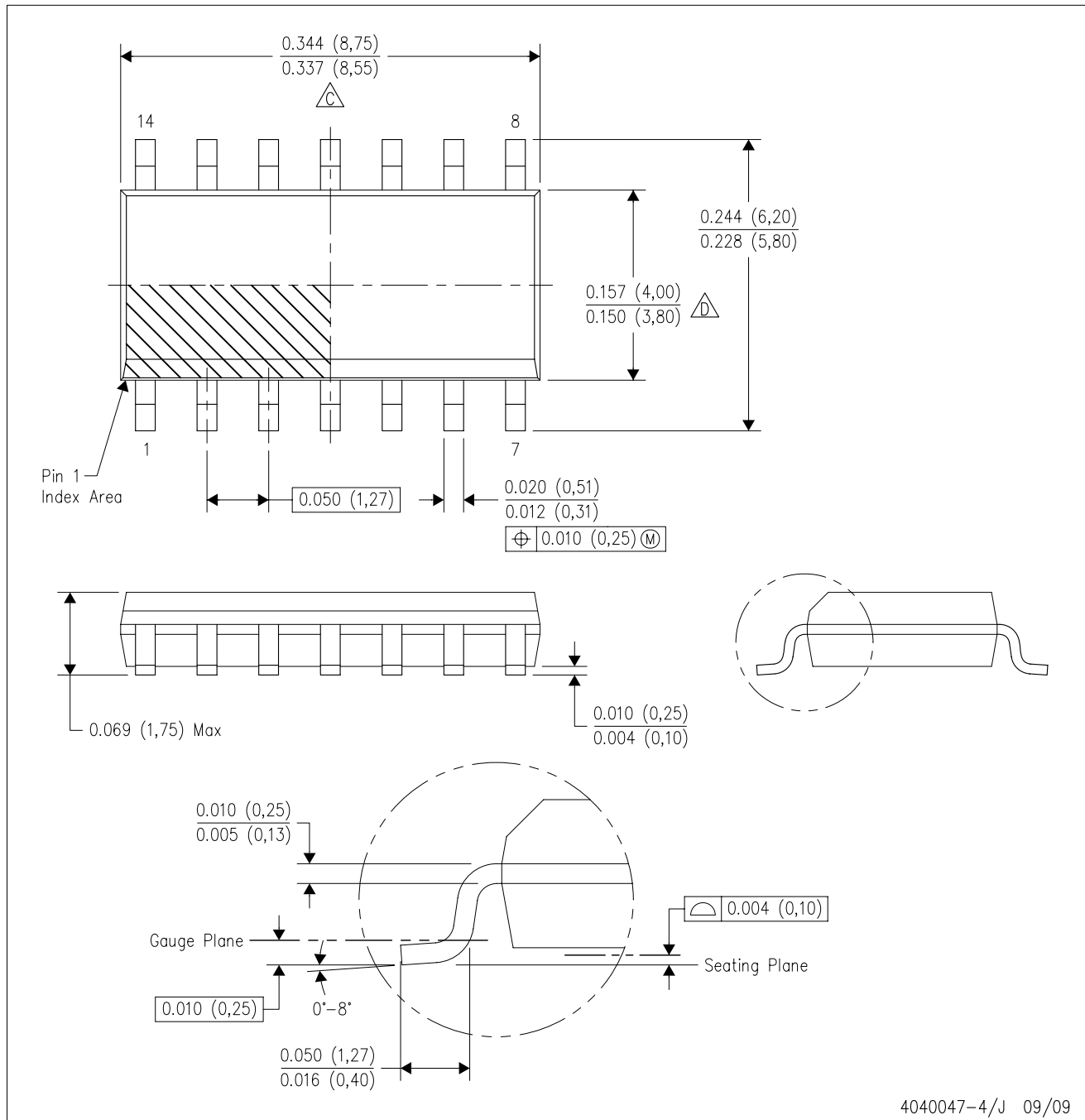
28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE

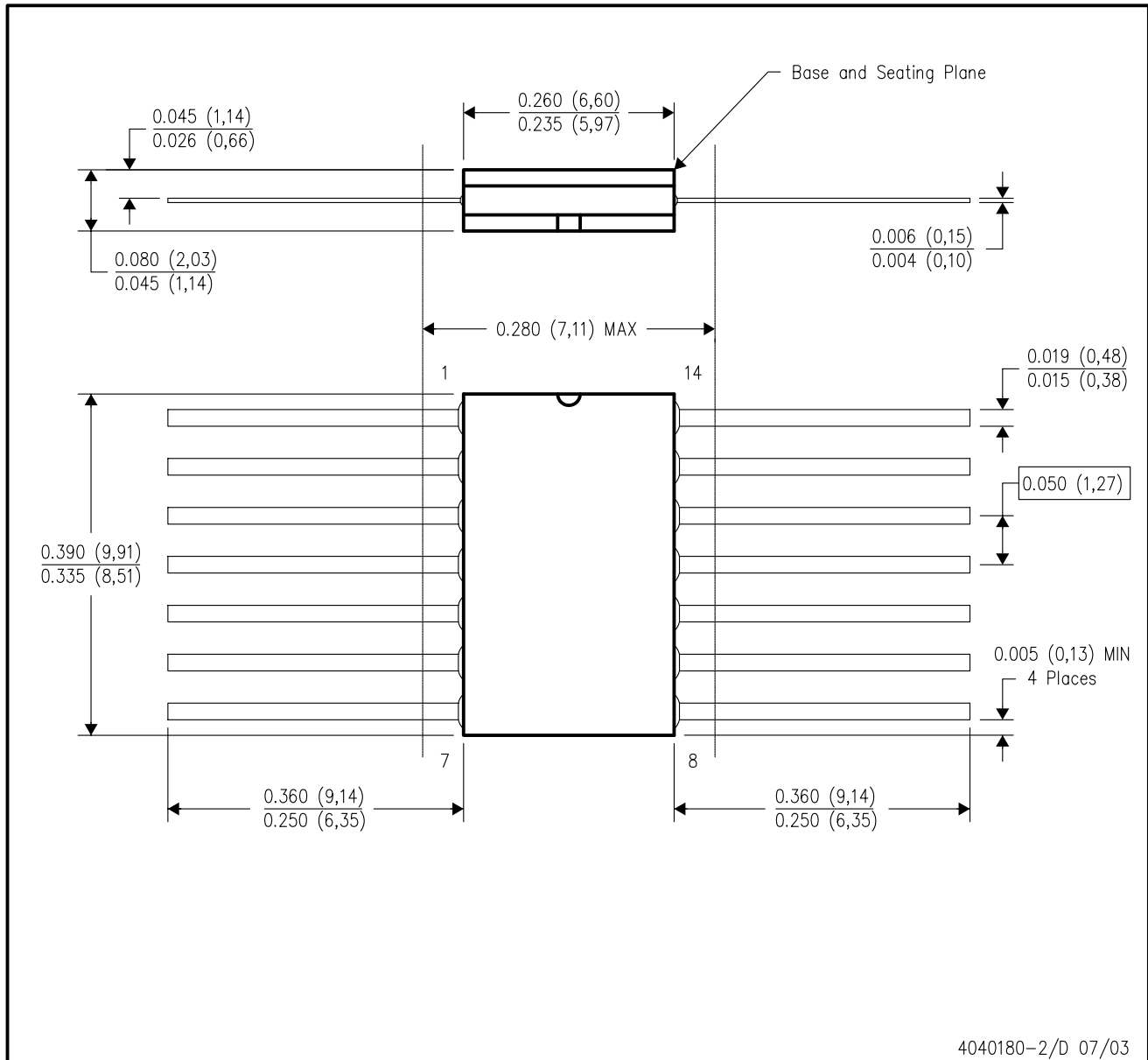


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/08003BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/08003BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/08003BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/31004B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/31004BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31004SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7408N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7408N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7408N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7408N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74LS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS08NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S08J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S08N	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						(RoHS)		
SN74S08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

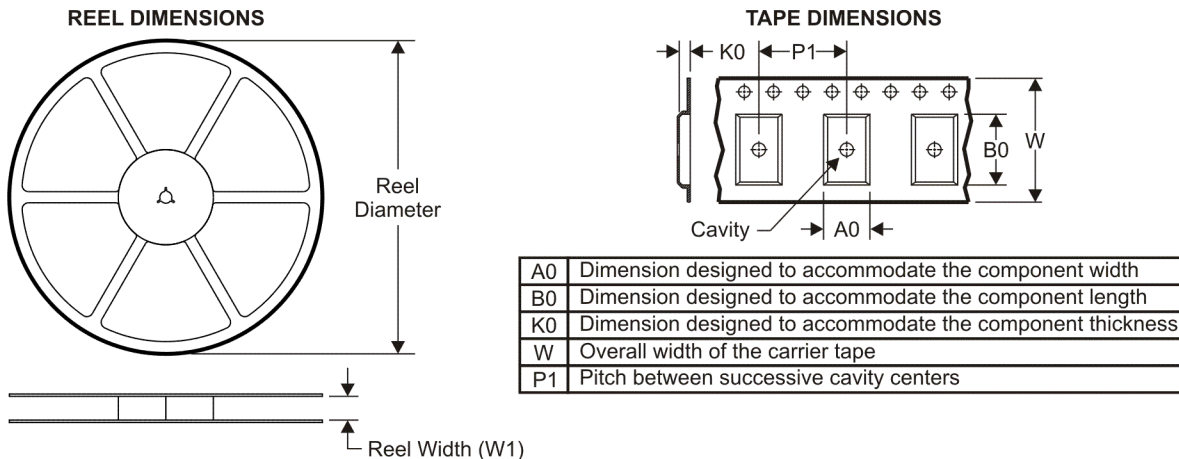
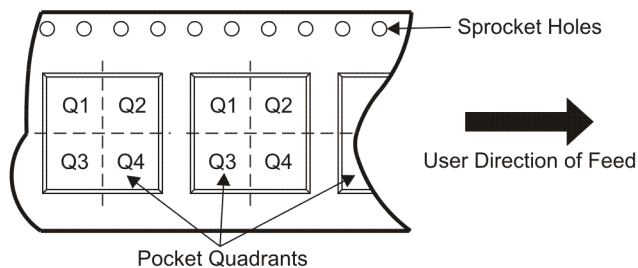
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI

to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS08DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS08NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS08DBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LS08DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS08NSR	SO	NS	14	2000	346.0	346.0	33.0



DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

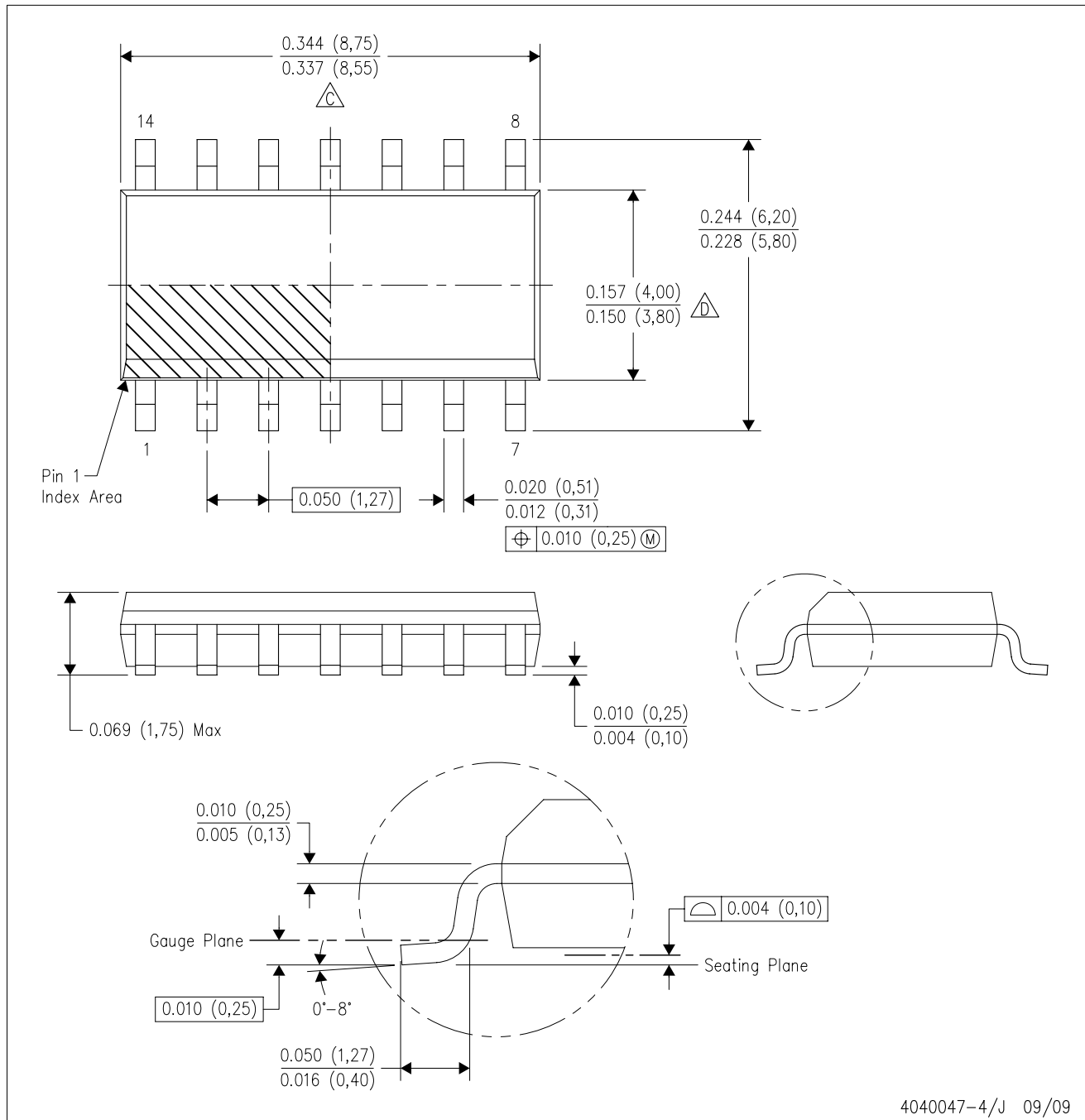


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

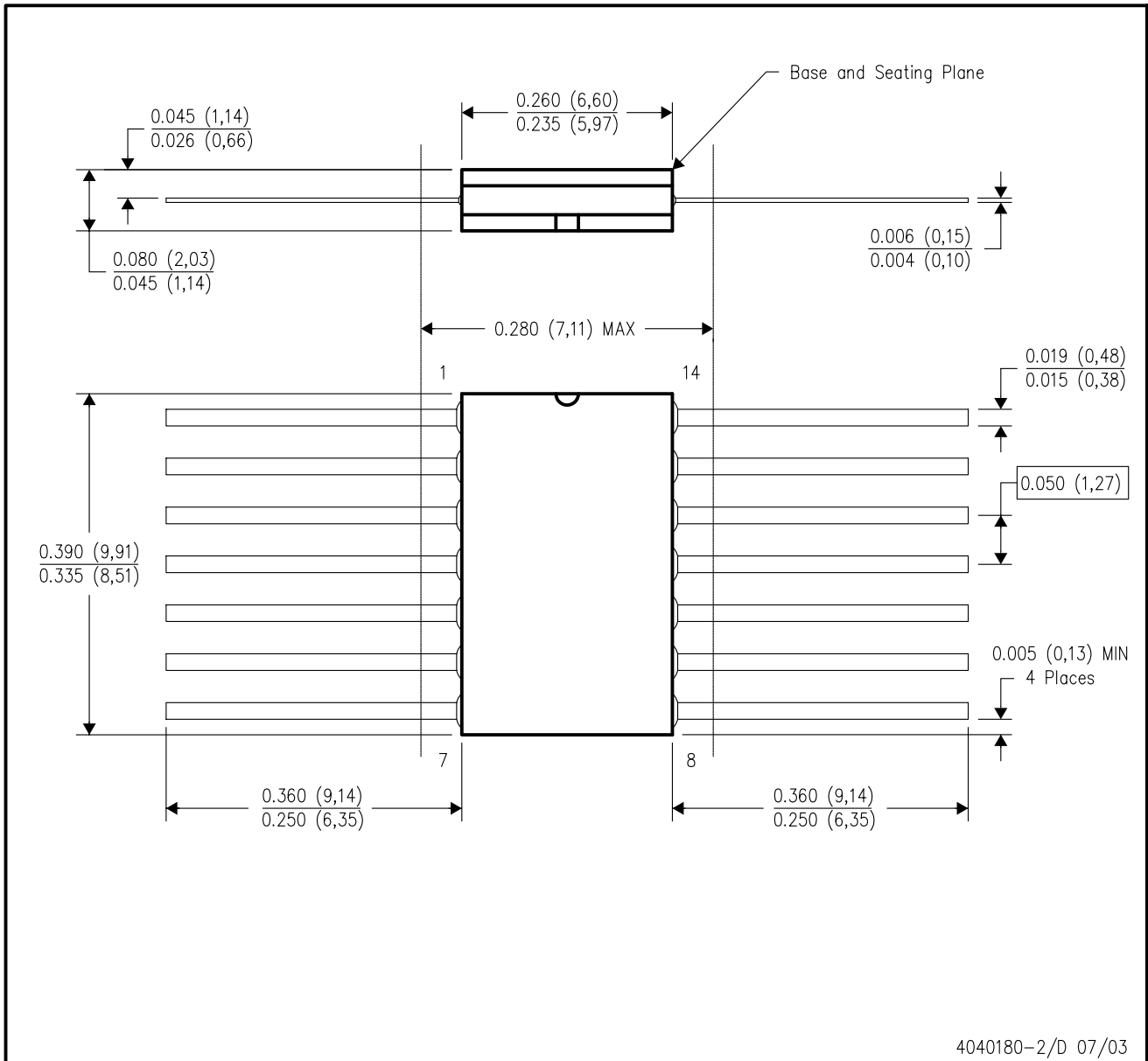
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



4040180-2/D 07/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

## IMPORTANT NOTICE

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